

# SOT744-1

plastic low profile fine-pitch ball grid array package; 64 balls;  
body 7 x 7 x 0.9 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	LFBGA64
<b>Package type industry code</b>	LFBGA64
<b>Package style descriptive code</b>	LFBGA (low profile fine-pitch ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-12-2001

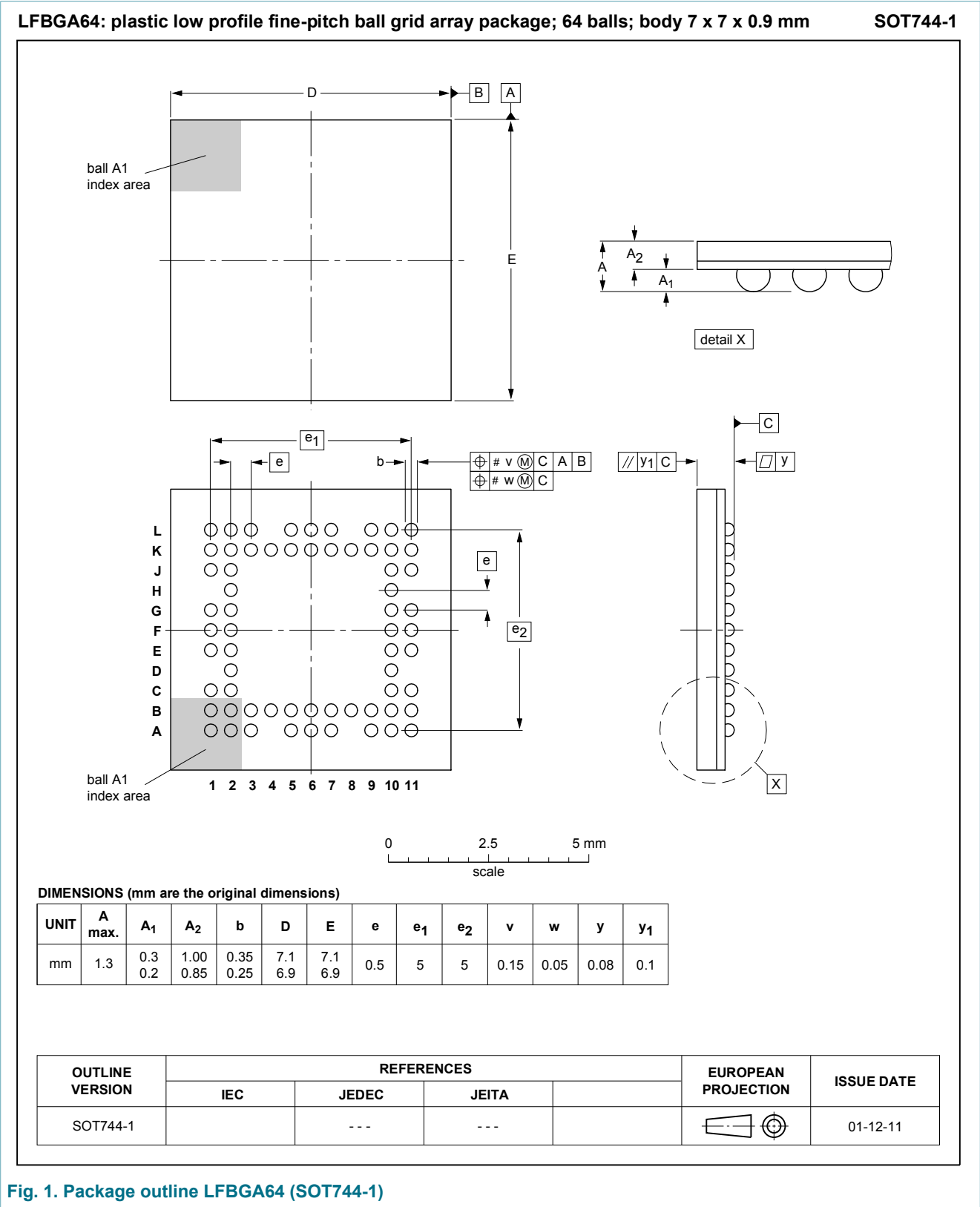
Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		6.9	-	7	7.1	mm
E	package width		6.9	-	7	7.1	mm
A	seated height		[tbd]	-	1.3	1.3	mm
A <sub>2</sub>	package height		0.85	-	0.9	1	mm
n <sub>2</sub>	actual quantity of termination		-	-	64	-	



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2. Package outline



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3. Soldering

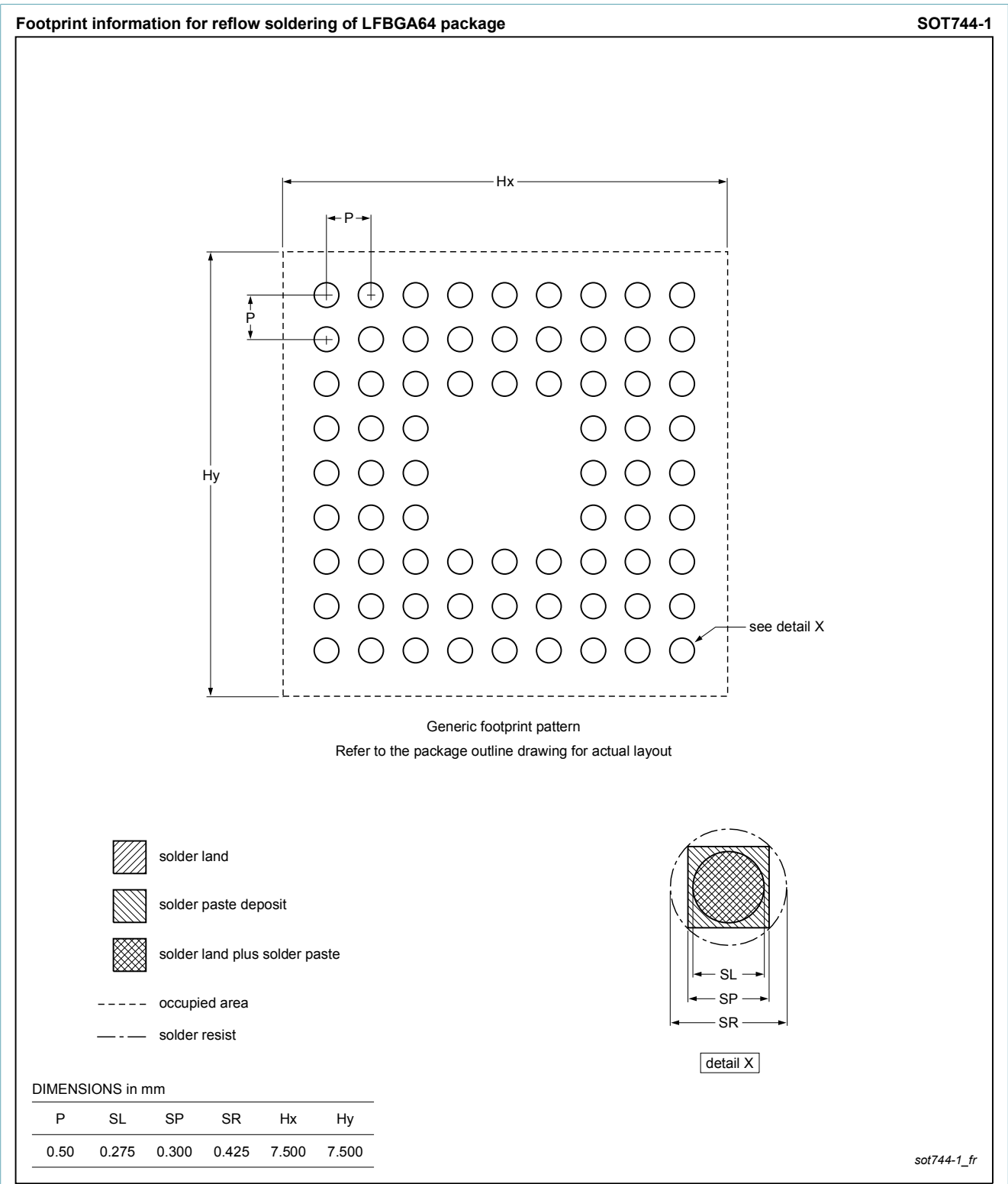


Fig. 2. Reflow soldering footprint for LFBGA64 (SOT744-1)

## 4. Legal information

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